

V_{DSS}	1200V
$R_{DS(on)}$ (Typ.)	62mΩ
I_D^{*1}	24A
P_D	93W

● Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

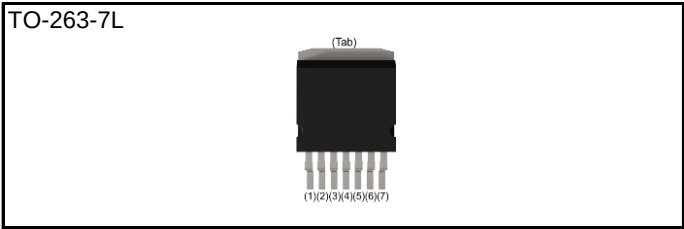
● Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

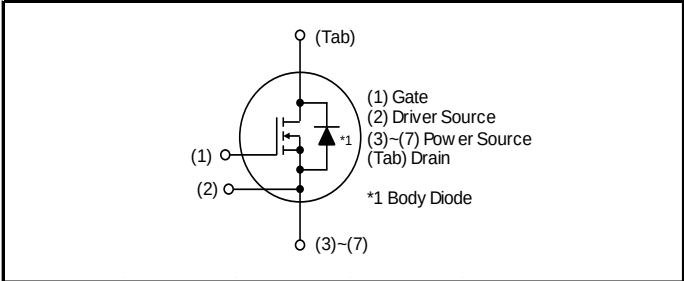
● Absolute maximum ratings ($T_c = 25^{\circ}\text{C}$)

Parameter		Symbol	Value	Unit
Drain - source voltage		V_{DSS}	1200	V
Continuous drain and source current $T_c = 100^{\circ}\text{C}$	$V_{GS} = V_{GS_{on}}$	I_D, I_S^{*1}	24	A
			17	A
Pulsed drain current	$V_{GS} = V_{GS_{on}}$	$I_{D,pulse}^{*2}$	52	A
Body diode pulsed forward current	$V_{GS} = 0\text{ V}$	$I_{S,pulse}^{*3}$	24	A
Body diode surge forward current	$V_{GS} = 0\text{ V}$	$I_{S,pulse}^{*4}$	52	A
Gate - source voltage (DC)		V_{GSS_DC}	-4 to +21	V
Gate - source surge voltage ($t_{surge} < 300\text{ns}$)		$V_{GSS_surge}^{*5}$	-4 to +23	V
Recommended turn-on gate - source drive voltage		$V_{GS_{on}}^{*6}$	+15 to +18	V
Recommended turn-off gate - source drive voltage		$V_{GS_{off}}$	0	V
Virtual junction temperature		T_{vj}	175	$^{\circ}\text{C}$
Range of storage temperature		T_{stg}	-40 to +175	$^{\circ}\text{C}$

● Outline



● Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

● Packaging specifications

Type	Packing	Embossed tape
	Reel size (mm)	330
	Tape width (mm)	24
	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	SCT4062KW7

● **Electrical characteristics** ($T_{vj} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}$, $I_D = 5.3\text{mA}$ $T_{vj} = 25^\circ\text{C}$	1200	-	-	V
Zero Gate voltage Drain current	I_{DSS}	$V_{GS} = 0\text{ V}$, $V_{DS} = 1200\text{V}$ $T_{vj} = 25^\circ\text{C}$	-	1	80	μA
		$T_{vj} = 150^\circ\text{C}$	-	10	-	
Gate - Source leakage current	I_{GSS+}	$V_{GS} = +21\text{V}$, $V_{DS} = 0\text{V}$	-	-	100	nA
Gate - Source leakage current	I_{GSS-}	$V_{GS} = -4\text{V}$, $V_{DS} = 0\text{V}$	-	-	-100	nA
Gate threshold voltage	$V_{GS(th)}^{*7}$	$V_{DS} = 10\text{V}$, $I_D = 6.45\text{mA}$	2.8	-	4.8	V
Static Drain - Source on - state resistance	$R_{DS(on)}^{*8}$	$V_{GS} = 18\text{V}$, $I_D = 12\text{A}$ $T_{vj} = 25^\circ\text{C}$	-	62	81	$\text{m}\Omega$
		$T_{vj} = 150^\circ\text{C}$	-	124	-	
Gate input resistance	R_G	f = 1MHz, open drain	-	4	-	Ω

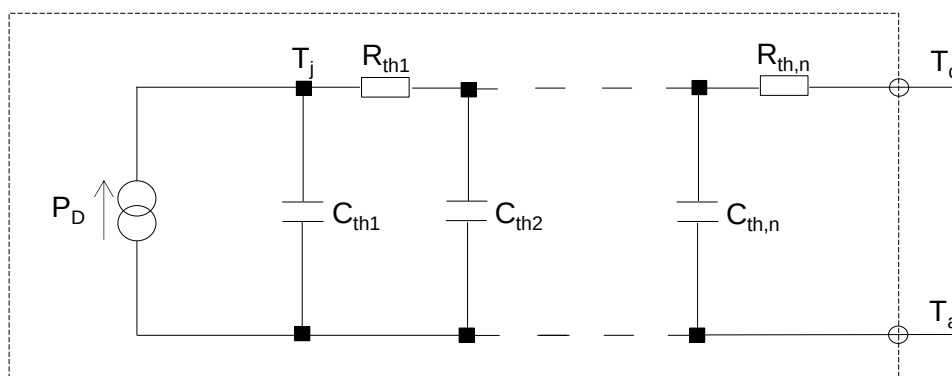
- Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}^{*9}	-	1.2	1.6	K/W

●Typical Transient Thermal Characteristics

Symbol	Value	Unit
R_{th1}	1.8×10^{-1}	K/W
R_{th2}	5.4×10^{-1}	
R_{th3}	4.8×10^{-1}	

Symbol	Value	Unit
C_{th1}	3.6×10^{-4}	Ws/K
C_{th2}	1.8×10^{-3}	
C_{th3}	2.3×10^{-2}	



●Electrical characteristics ($T_{vj} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Transconductance	g_{fs}^{*8}	$V_{DS} = 10\text{V}, I_D = 12\text{A}$	-	6.5	-	S
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$	-	1498	-	pF
Output capacitance	C_{oss}	$V_{DS} = 800\text{V}$	-	45	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	3	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{GS} = 0\text{V}$ $V_{DS} = 0\text{V to } 800\text{V}$	-	54	-	pF
Total Gate charge	Q_g^{*8}	$V_{DS} = 800\text{V}$ $I_D = 12\text{A}$	-	64	-	nC
Gate - Source charge	Q_{gs}^{*8}	$V_{GS} = 18\text{V}$	-	14	-	
Gate - Drain charge	Q_{gd}^{*8}	See Fig. 1-1, 1-2.	-	17	-	
Turn - on delay time	$t_{d(on)}^{*8}$	$V_{DS} = 800\text{V}$ $I_D = 12\text{A}$	-	4.4	-	ns
Rise time	t_r^{*8}	$V_{GS} = +18\text{V} / 0\text{V}$	-	11	-	
Turn - off delay time	$t_{d(off)}^{*8}$	$R_G = 0\Omega, L = 250\mu\text{H}$ E_{on} includes diode reverse recovery	-	22	-	
Fall time	t_f^{*8}	$L_\sigma = 50\text{nH}, C_\sigma = 10\text{pF}$	-	10	-	
Turn - on switching loss	E_{on}^{*8}	See Fig. 2-1, 2-2, 2-3.	-	132	-	μJ
Turn - off switching loss	E_{off}^{*8}		-	6	-	

●Body diode electrical characteristics (Source-Drain) ($T_{vj} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Forward voltage	V_{SD}^{*8}	$V_{GS} = 0\text{V}, I_D = 12\text{A}$	-	3.3	-	V
Reverse recovery time	t_{rr}^{*8}	$I_F = 12\text{A}$ $V_R = 800\text{V}$	-	8.1	-	ns
Reverse recovery charge	Q_{rr}^{*8}	$di/dt = 3800\text{A}/\mu\text{s}$	-	105	-	nC
Peak reverse recovery current	I_{rrm}^{*8}	$L_{\sigma} = 50\text{nH}, C_{\sigma} = 10\text{pF}$ See Fig. 3-1, 3-2.	-	26	-	A

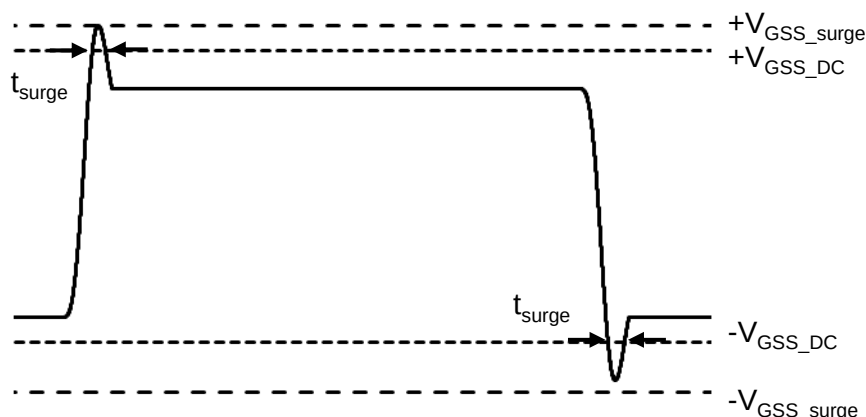
*1 Limited by maximum T_{vj} and for Max. R_{thJC} .

*2 $PW \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 Only for body-diode, Repetitive pulse, $PW \leq 500\text{ns}$, Duty cycle $\leq 5\%$

*4 When used as a protective function, $PW \leq 10\mu\text{s}$

*5 Example of acceptable V_{GS} waveform



Please note especially when using driver source that V_{GSS_surge} must be in the range of absolute maximum rating.

*6 Please be advised not to use SiC-MOSFETs with V_{GS} below 10V as doing so may cause thermal runaway.

*7 Tested after applying $V_{GS} = 21\text{V}$ for 100ms.

*8 Pulsed

*9 Measured conformable to JESD51-14.

See the application note "rthjc_measurement_and_usage_an-e.pdf". [Link](#)

URL: https://fscdn.rohm.com/en/products/databook/applinote/discrete/common/rthjc_measurement_and_usage_an-e.pdf

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

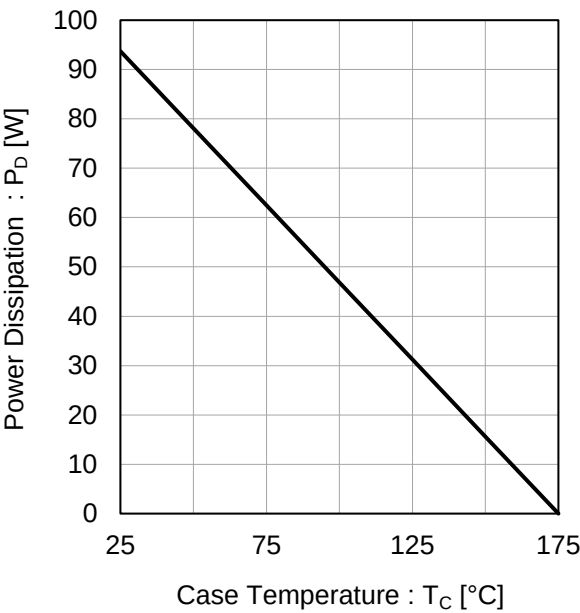


Fig.2 Maximum Safe Operating Area

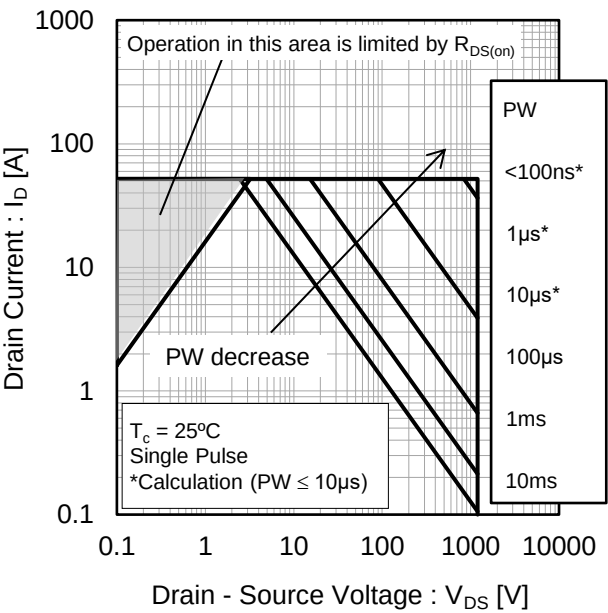
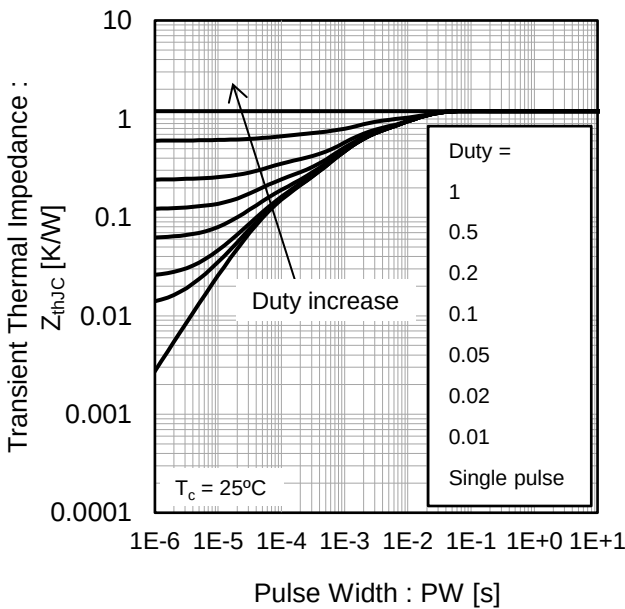


Fig.3 Typical Transient Thermal Impedance vs. Pulse Width



●Electrical characteristic curves

Fig.4 $T_{vj} = 25^{\circ}\text{C}$ Typical Output Characteristics(I)

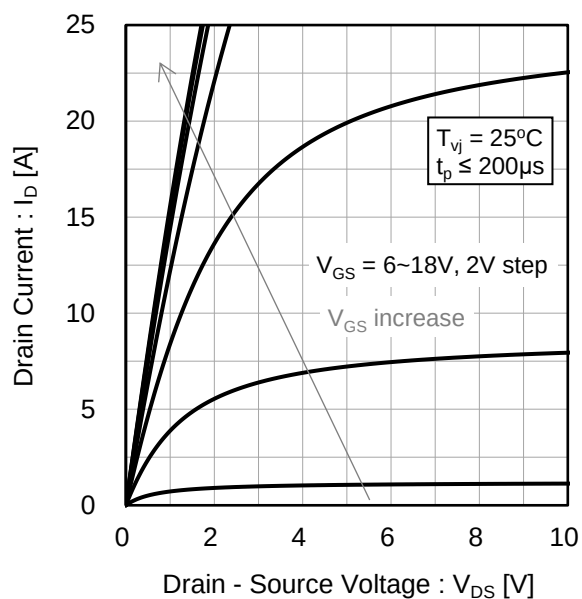


Fig.5 $T_{vj} = 25^{\circ}\text{C}$ Typical Output Characteristics(II)

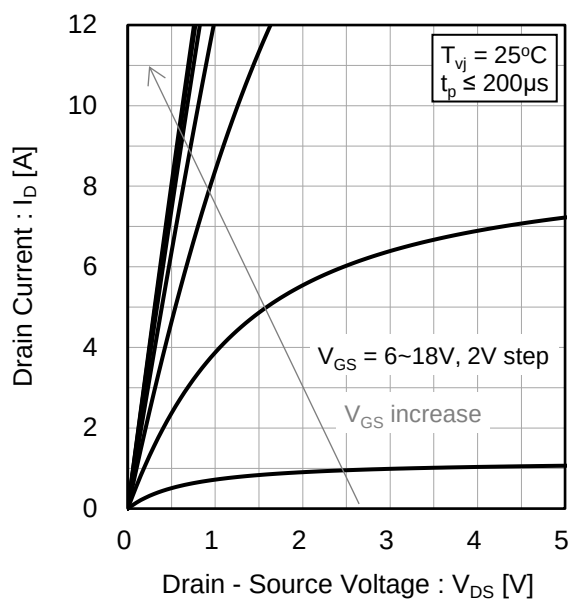
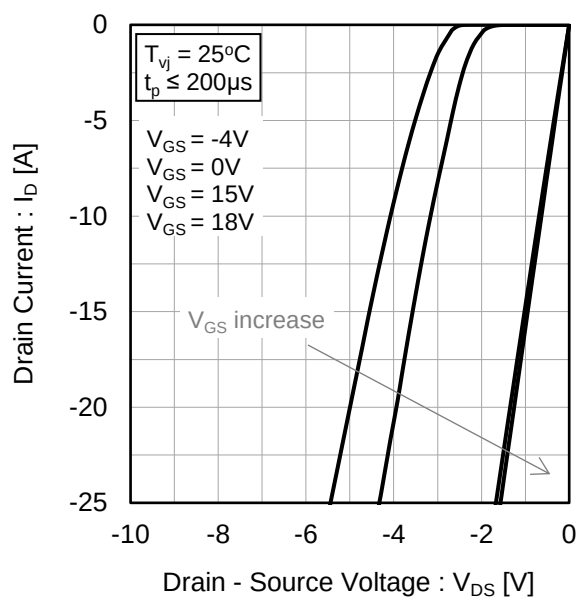


Fig.6 $T_{vj} = 25^{\circ}\text{C}$ 3rd Quadrant Characteristics



●Electrical characteristic curves

Fig.7 $T_{vj} = 150^{\circ}\text{C}$ Typical Output Characteristics(I)

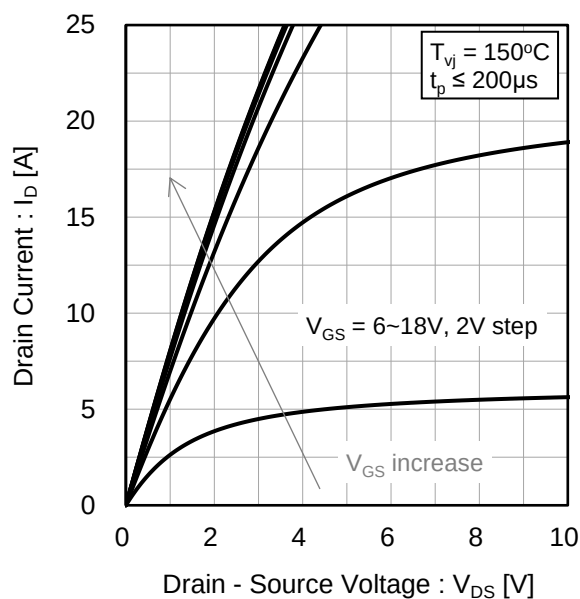


Fig.8 $T_{vj} = 150^{\circ}\text{C}$ Typical Output Characteristics(II)

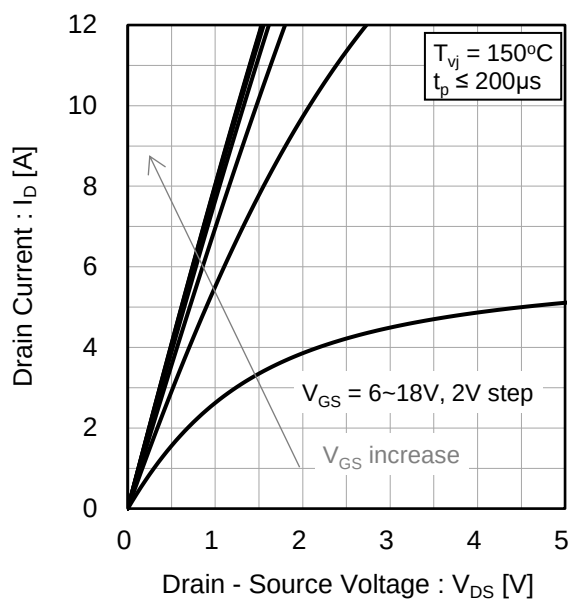


Fig.9 $T_{vj} = 150^{\circ}\text{C}$ 3rd Quadrant Characteristics

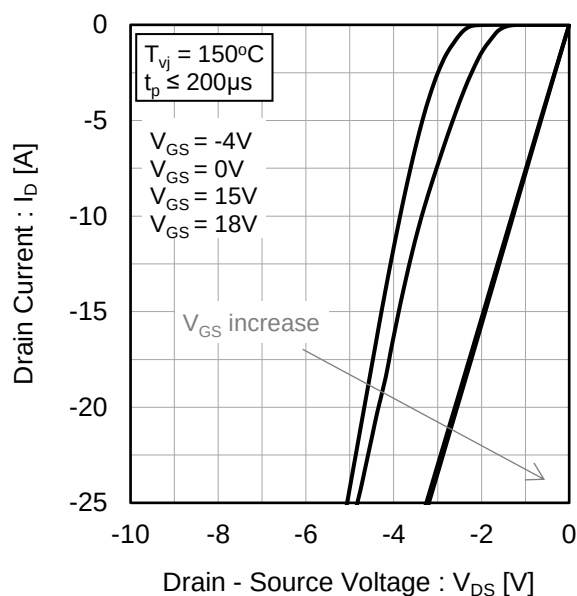
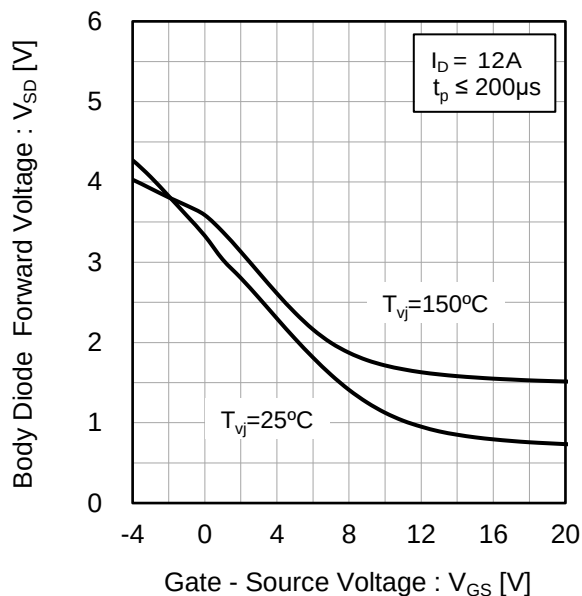


Fig.10 Body Diode Forward Voltage vs. Gate - Source Voltage



●Electrical characteristic curves

Fig.11 Typical Transfer Characteristics (I)

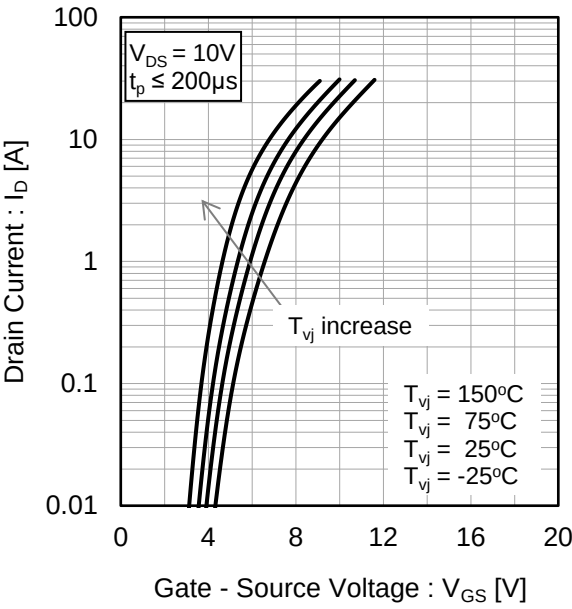


Fig.12 Typical Transfer Characteristics (II)

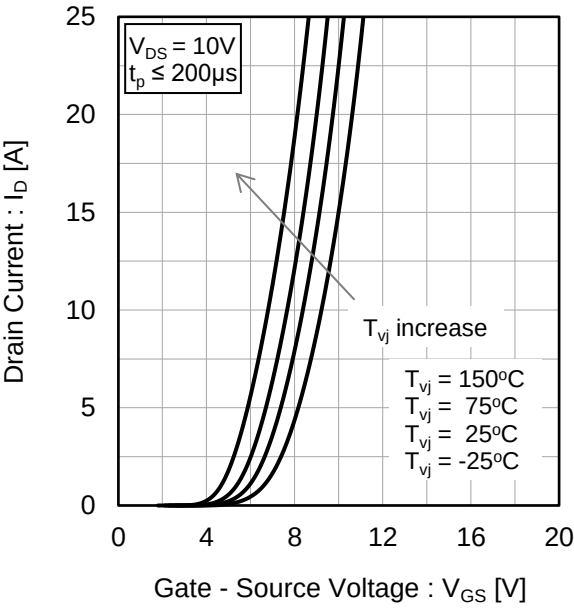


Fig.13 Gate Threshold Voltage vs. Virtual Junction Temperature

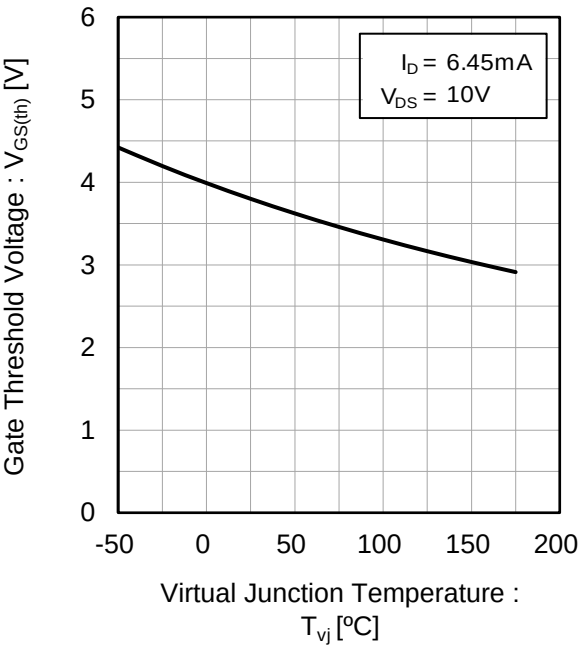
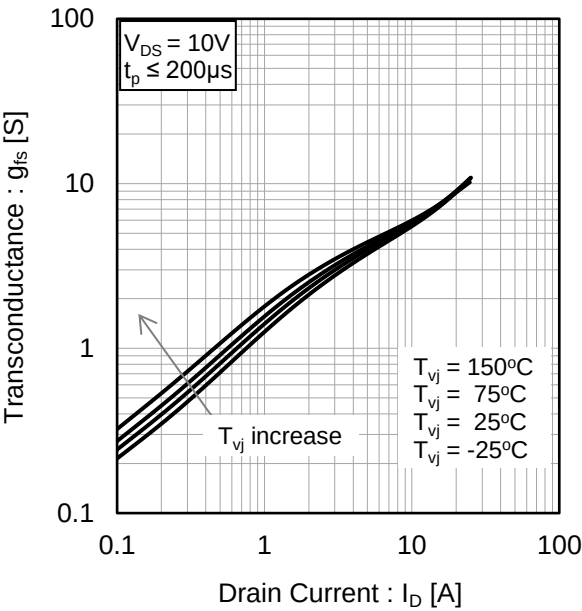


Fig.14 Transconductance vs. Drain Current



●Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

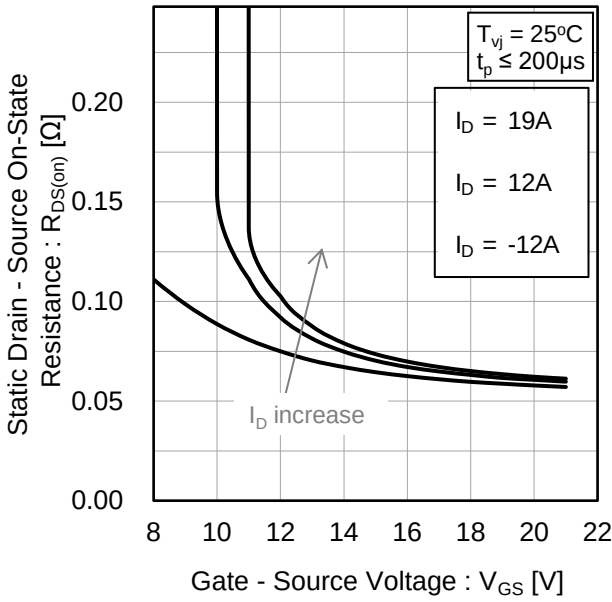


Fig.16 Static Drain - Source On - State Resistance vs. Virtual Junction Temperature

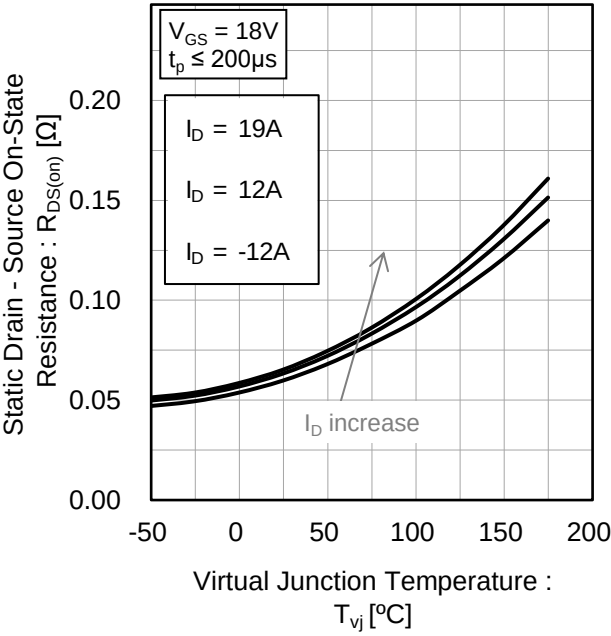


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current

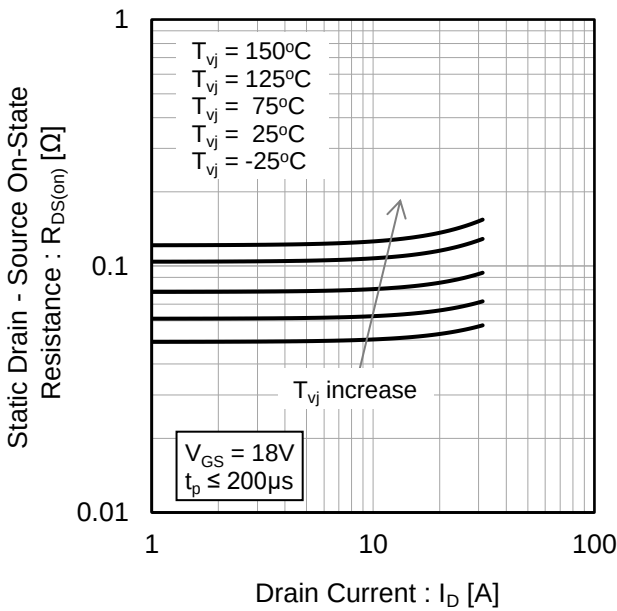
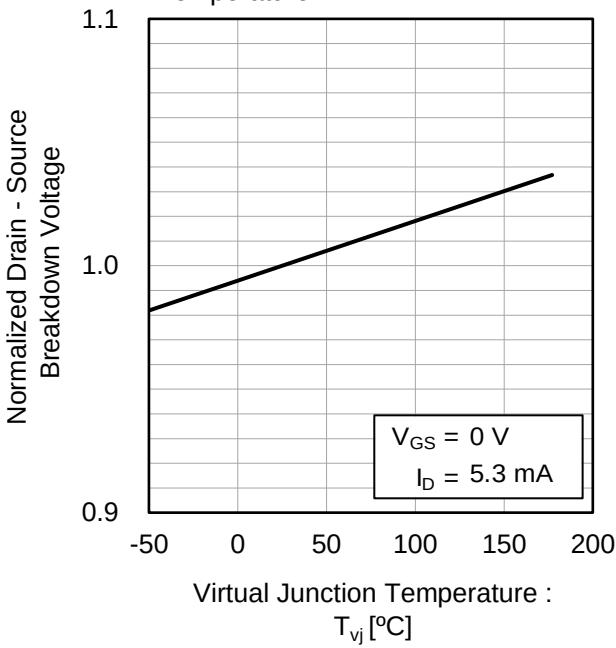


Fig.18 Normalized Drain - Source Breakdown Voltage vs. Virtual Junction Temperature



●Electrical characteristic curves

Fig.19 Typical Capacitance vs. Drain - Source Voltage

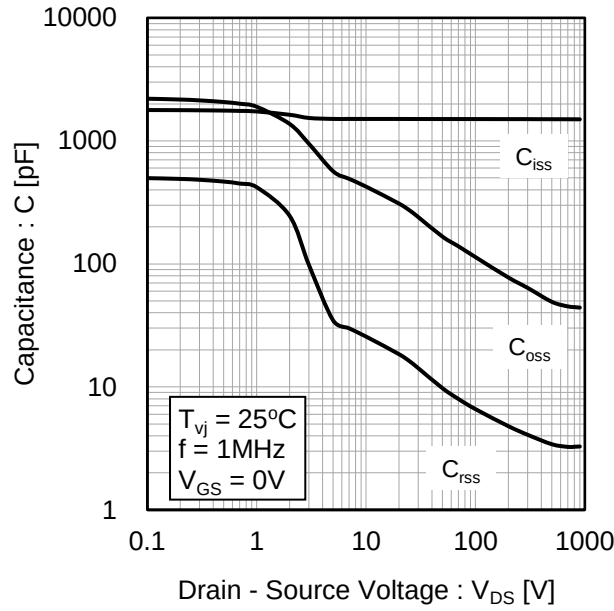


Fig.20 C_{oss} Stored Energy

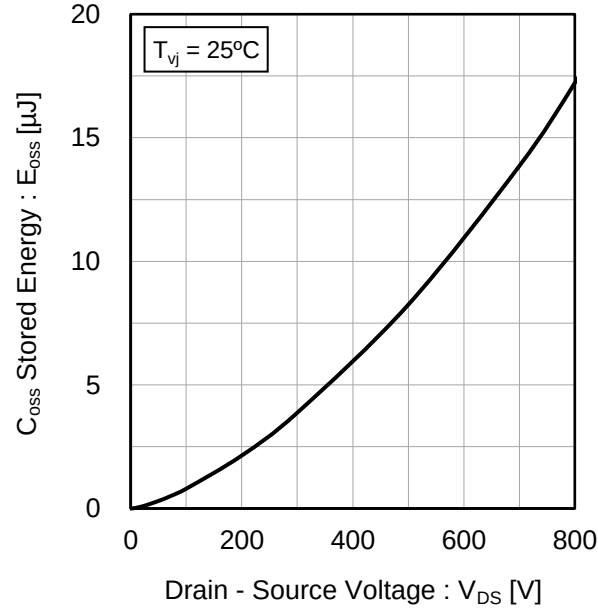
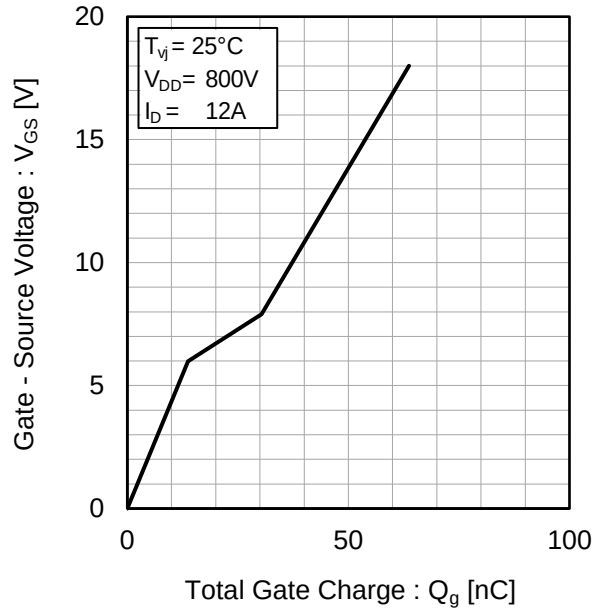


Fig.21 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.22 Typical Switching Time vs. External Gate Resistance

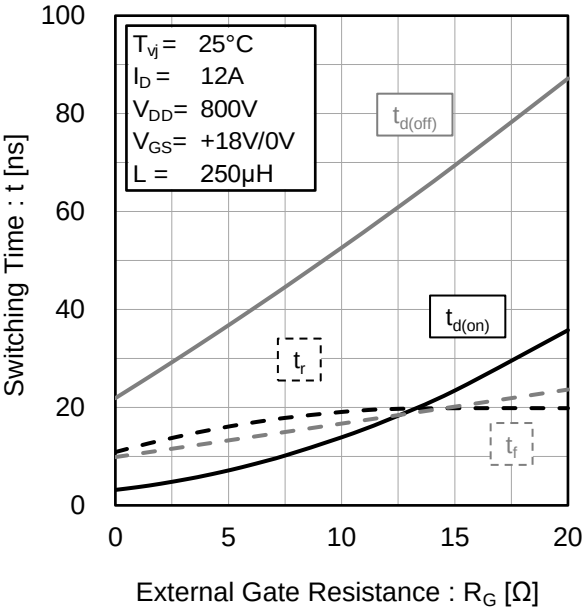


Fig.23 Typical Switching Loss vs. Drain - Source Voltage

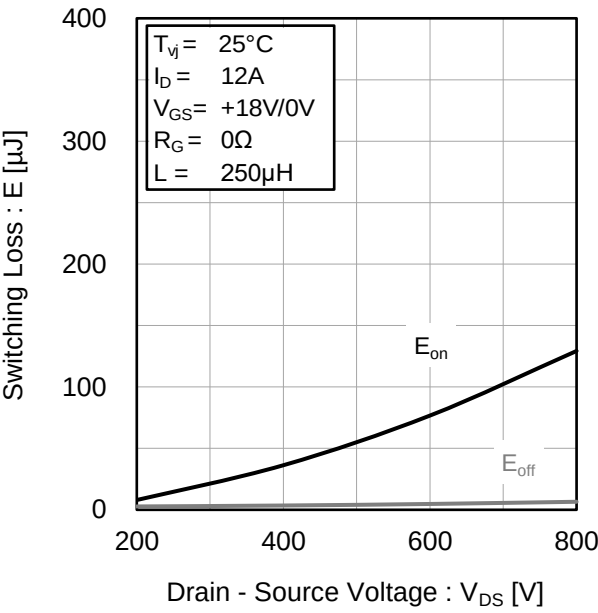


Fig.24 Typical Switching Loss vs. Drain Current

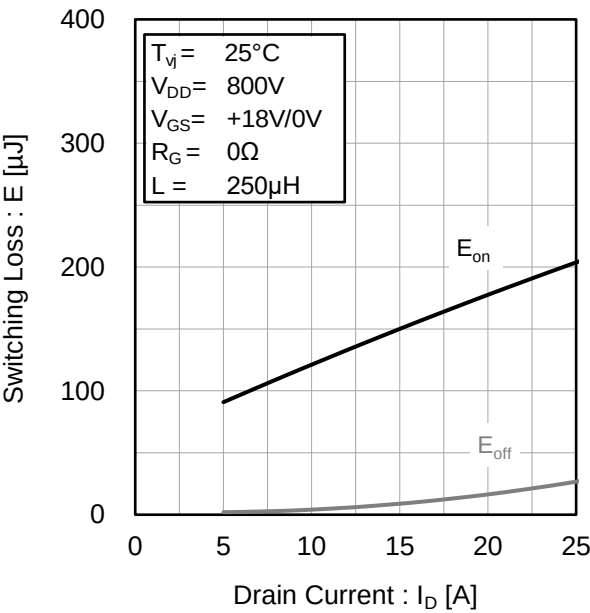
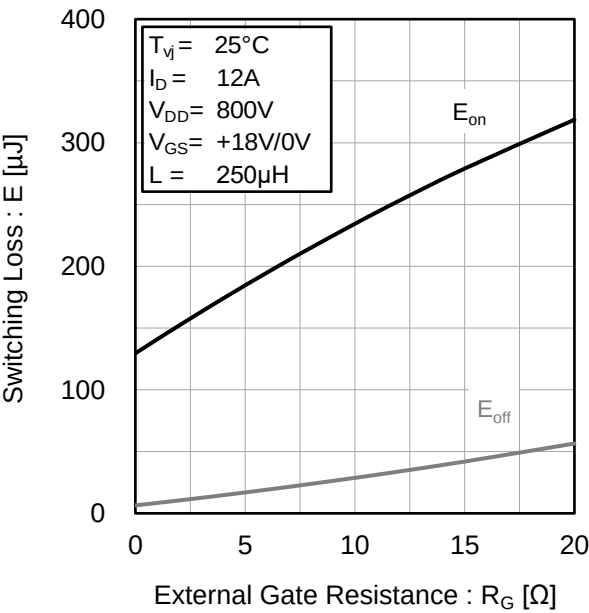


Fig.25 Typical Switching Loss vs. External Gate Resistance



● Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

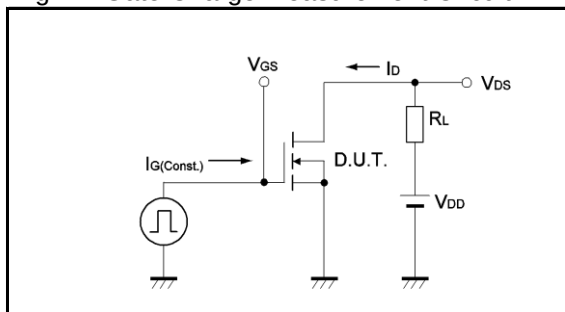


Fig.1-2 Gate Charge Waveform

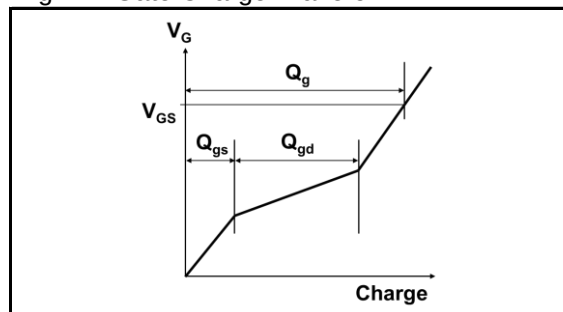


Fig.2-1 Switching Characteristics Measurement Circuit

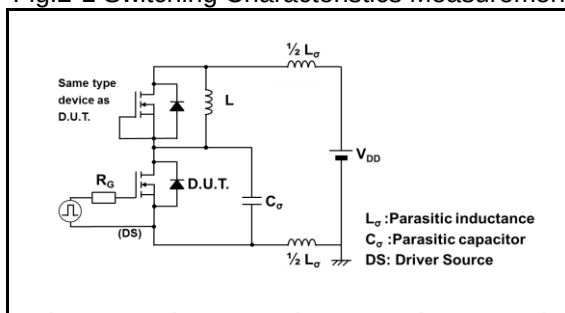


Fig.2-2 Waveforms for Switching Time

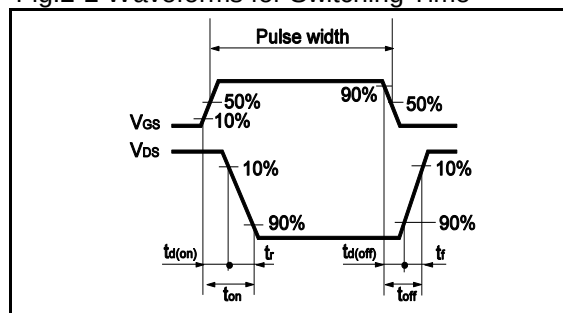


Fig.2-3 Waveforms for Switching Energy Loss

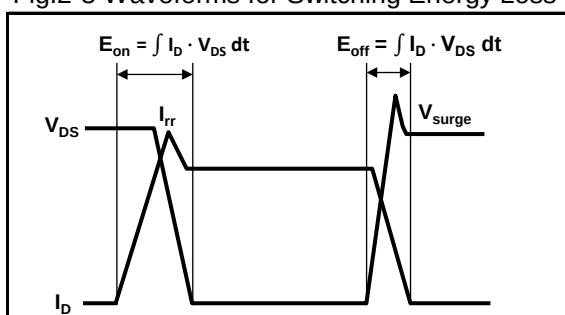


Fig.3-1 Reverse Recovery Time Measurement Circuit

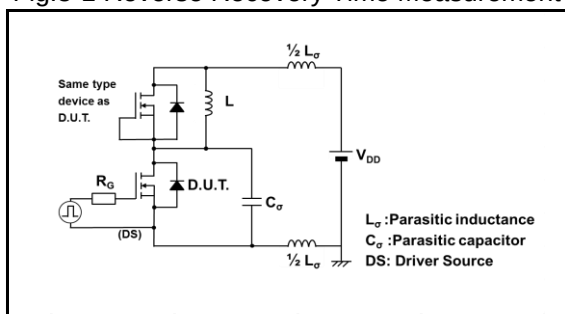
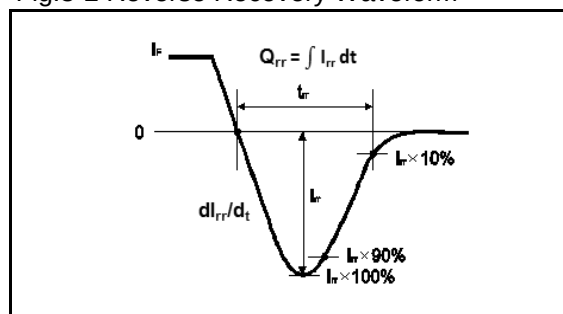
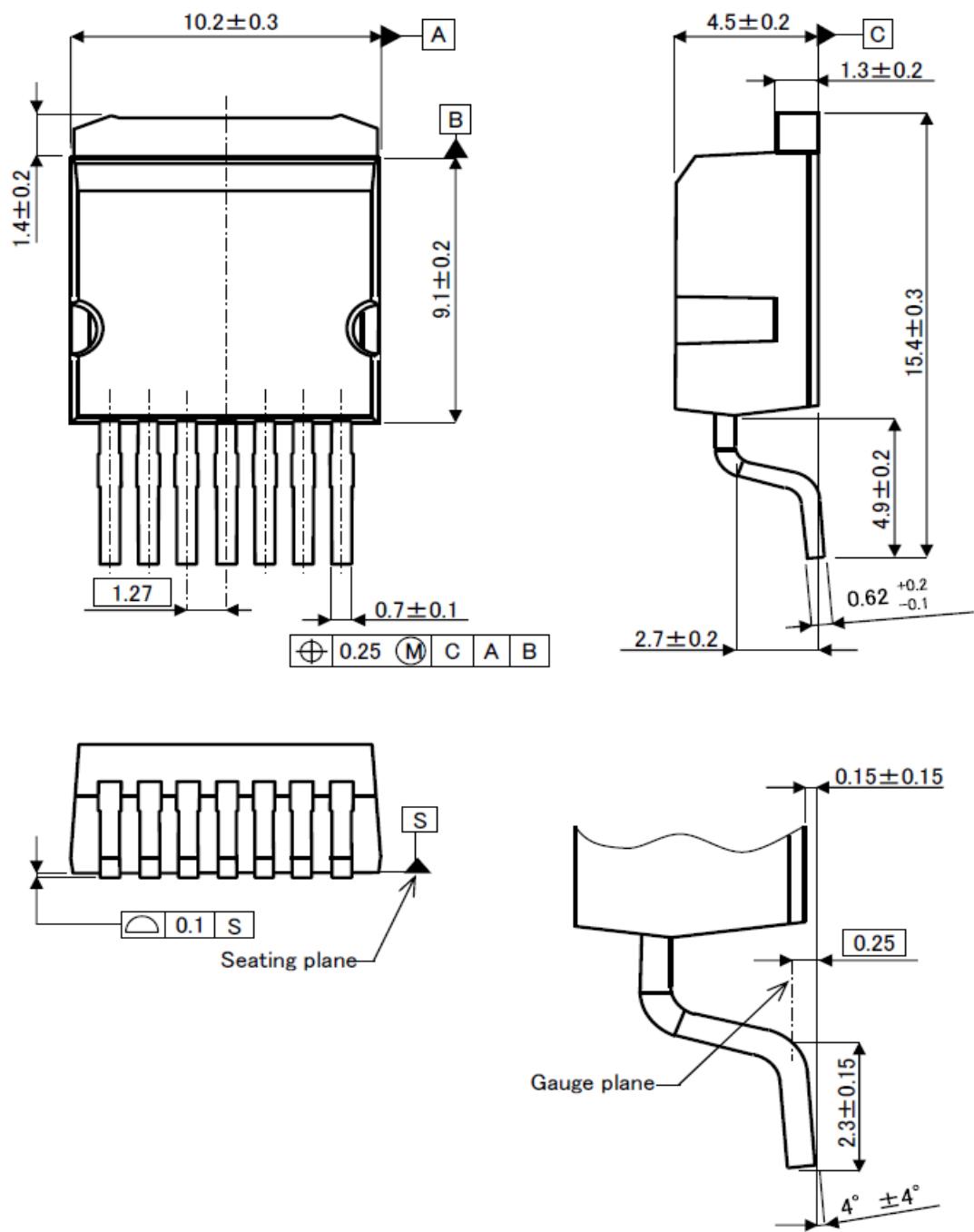


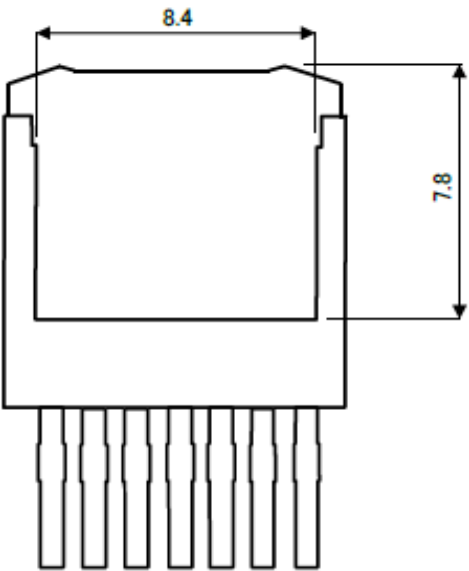
Fig.3-2 Reverse Recovery Waveform



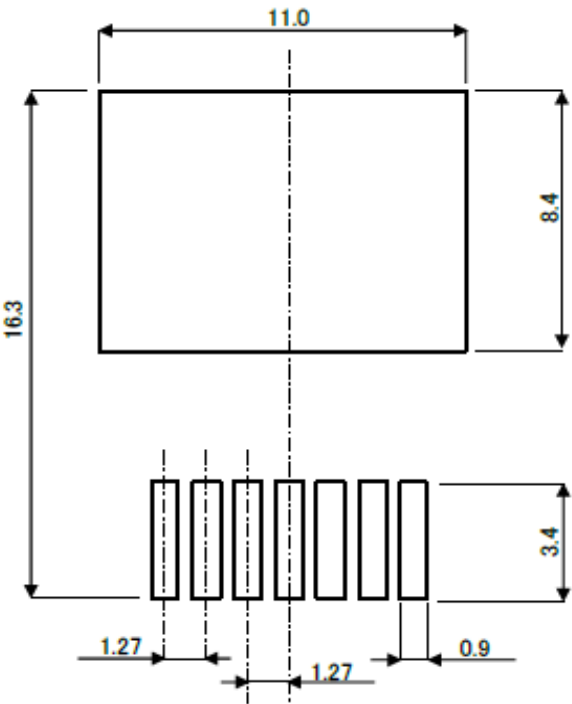
●Package Dimensions



Unit: mm

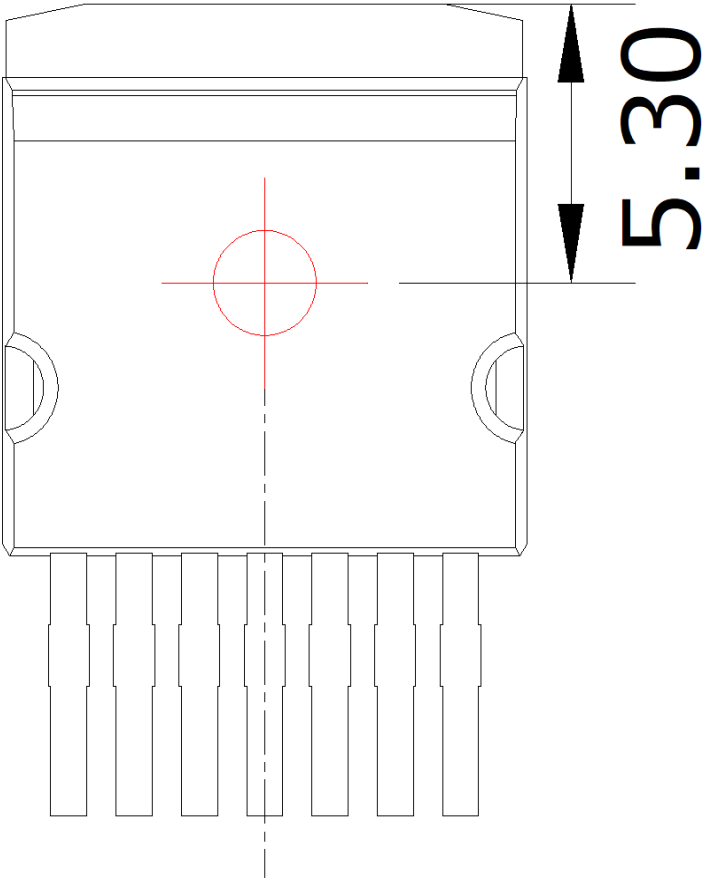
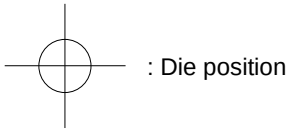


RECOMMENDED FOOTPRINT DIMENSIONS



Unit: mm

●Die Bonding Layout



- Front view of the packaging.
- Dimensions are design values.
- If the heat sink is to be installed, it should be in contact with the die bonding point.

Unit: mm